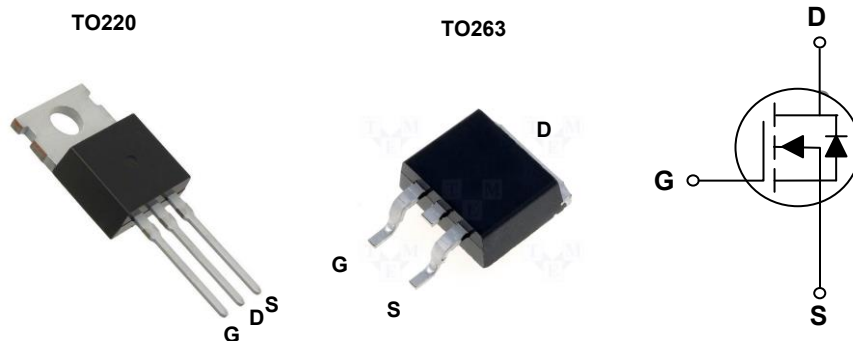


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	40V
I_D (at $V_{GS}=10V$)	200A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	2.5m Ω (Max)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	TC=25 $^\circ\text{C}$	I_D	200
	TC=100 $^\circ\text{C}$	I_D	126
Maximum Power Dissipation	P_D	184	W
Single pulse avalanche energy	E_{AS}	390	mJ
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		1.1	$^\circ\text{C} / \text{W}$
Thermal Resistance unction-to-Ambient	$R_{\theta JA}$		62	$^\circ\text{C} / \text{W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40V, V_{GS}=0V$			1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.6	2.5	V
$R_{DS(ON)}$	Drain-Source On-State esistance	$V_{GS}=10V, I_D=30A$		1.8	2.5	m Ω
		$V_{GS}=4.5V, I_D=15A$		2.0	3.0	m Ω
DYNAMIC PARAMETERS						
C_{ISS}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V,$ $F=1.0MHz$		8000		pF
C_{OSS}	Output Capacitance			550		pF
C_{RSS}	Reverse Transfer Capacitance			420		pF
SWITCHING PARAMETERS						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=20V, I_D=10A,$ $V_{GS}=10V,$ $R_G=10\Omega$		24		nS
t_r	Turn-on Rise Time			62		nS
$t_{d(off)}$	Turn-Off Delay Time			220		nS
t_f	Turn-Off Fall Time			160		nS
Q_g	Total Gate Charge	$V_{DS}=20V, I_D=10A,$ $V_{GS}=4.5V$		70		nC
Q_{gs}	Gate-Source Charge			15		nC
Q_{gd}	Gate-Drain Charge			40		nC
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_{SD}=1A$		0.72	1.3	V
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V,$ $F=1MHz$		1.2		Ω

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=30V, L=0.1mH, I_{AS}=85A.$, Starting T_J=25°C
3. The data tested by pulsed , pulse width $\cong 300\mu s$, duty cycle $\cong 2\%$.
4. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

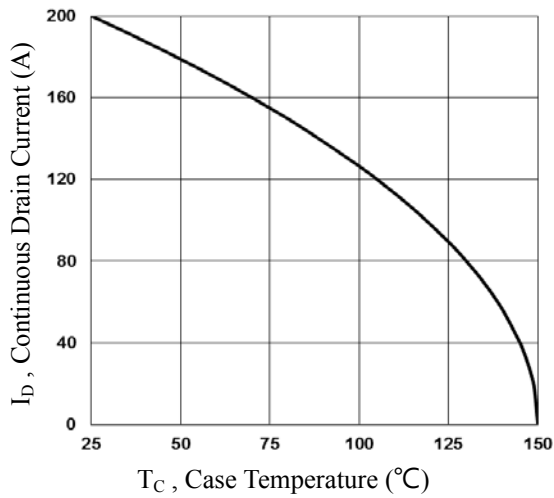


Fig.1 Continuous Drain Current vs. T_C

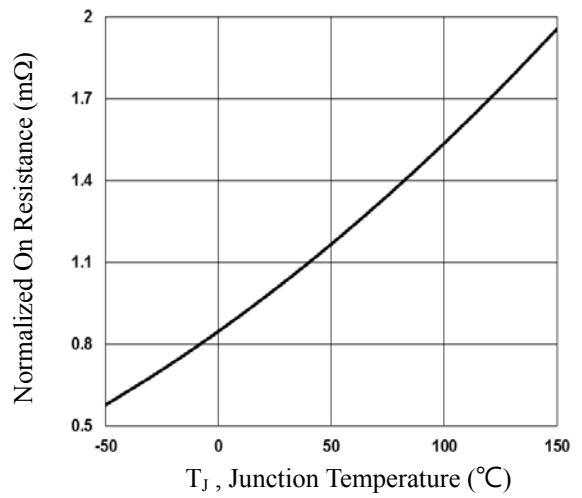


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

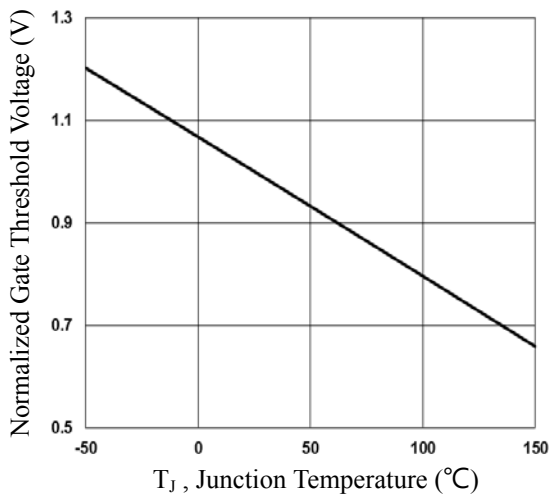


Fig.3 Normalized V_{th} vs. T_J

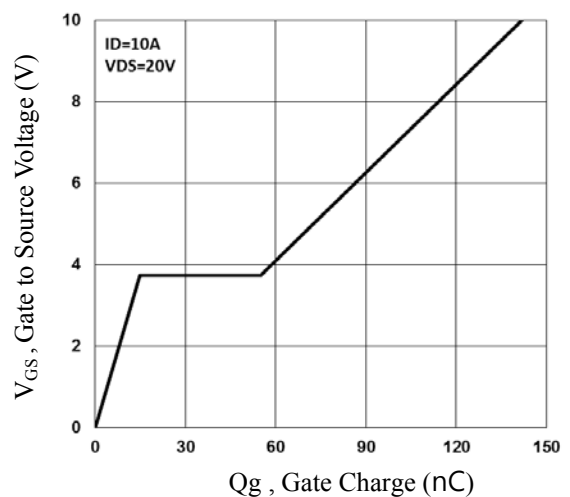


Fig.4 Gate Charge Waveform

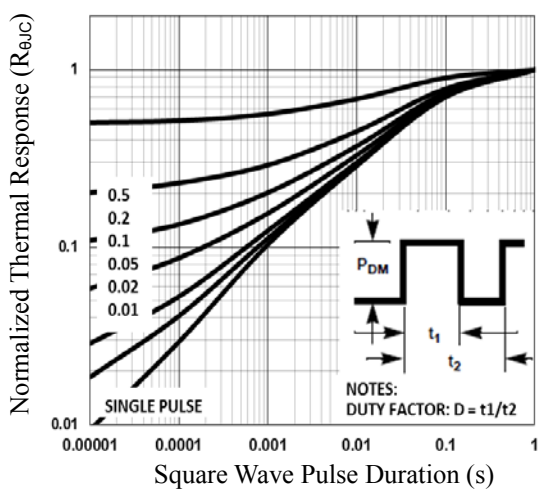


Fig.5 Normalized Transient Impedance

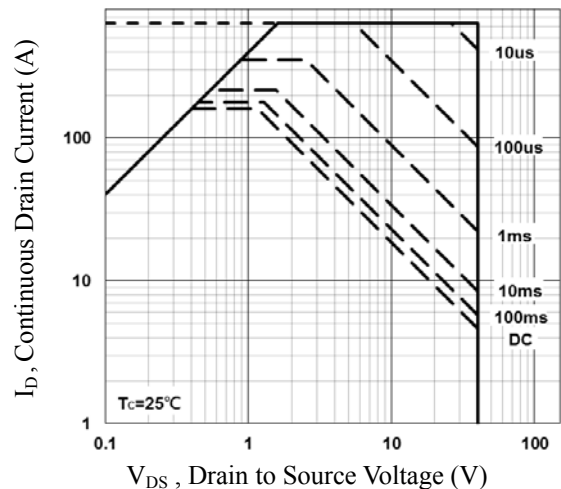


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

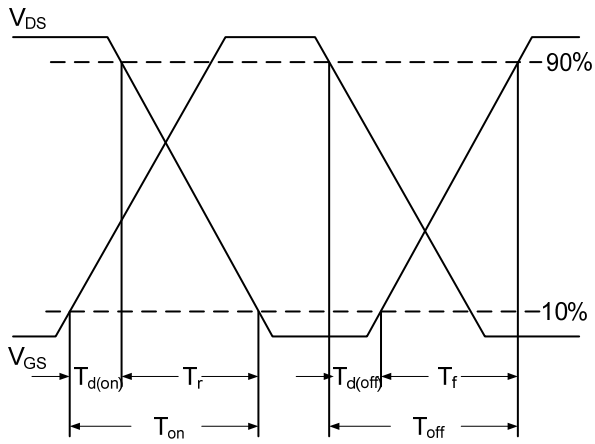


Fig.7 Switching Time Waveform

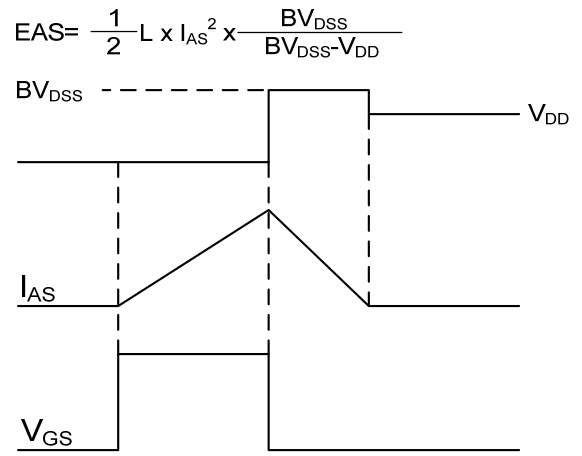
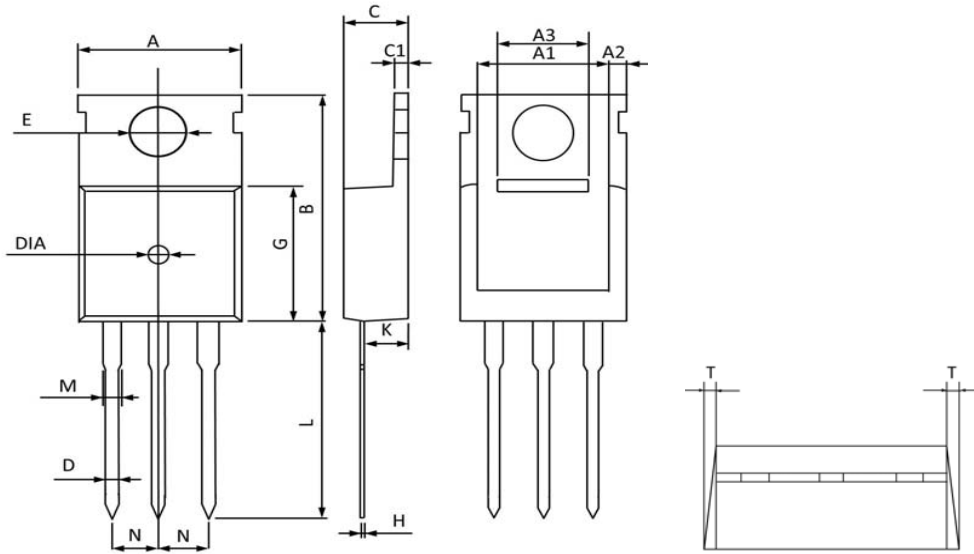


Fig.8 EAS Waveform

TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.

TO263 PACKAGE INFORMATION

